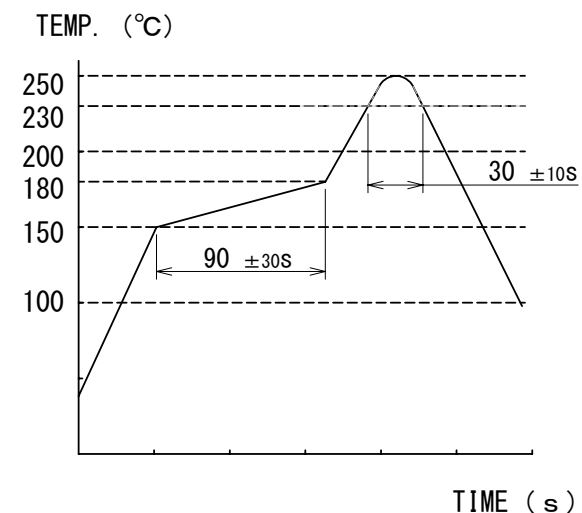


1. RECOMMENDED REFLOW PROFILE (SEE RIGHT GRAPH)
CYCLE TIME: UP TO 2 CYCLES OF REFLOW SOLDERING ARE POSSIBLE
UNDER THE CONDITIONS, PROVIDED THAT THERE IS
A RETURN TO NOMAL TEMPERATURE BETWEEN THE FIRST
AND SECOND CYCLE.
PEAK TEMPERATURE: 250°C
230°C MIN, FOR 20 TO 40 SECONDS.
PREHEATING AREA 150~180°C FOR 60 TO 120 SECONDS.
2. HAND SOLDERING: 280~300°C, 2SECONDS MAX.
3. CONTACT COPLANARITY: 0.1mm MAX.
4. RECOMMENDED THICKNESS OF PCB: 1.6mm
5. RECOMMENDED THICKNESS OF SOLDERING PASTE: 0.12mm

[illegible]